

ON Semiconductor
Formerly a Division of Motorola



Subject: ON Semiconductor PRODUCT/PROCESS CHANGE NOTIFICATION 10049

TITLE: QUALIFY CASE-77 PLATELESS LEADFRAME AND PROCESS

EFFECTIVE DATE: 20-JAN-00

AFFECTED CHANGE CATEGORIES
Assembly Process

AFFECTED PRODUCT DIVISIONS
BIPOLAR DISCRETES D

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office.

Ref: R38181

SAMPLES: Contact Below
Contact your local ON Semiconductor Sales Office.

Ref: R38181@email.sps.mot.com

For any questions concerning this notification:

REFERENCE: JOSE RAMIREZ PHONE: 602-244-4819

DISCLAIMER:

ON SEMICONDUCTOR WILL CONSIDER THIS CHANGE APPROVED UNLESS SPECIFIC
CONDITIONS OF ACCEPTANCE ARE PROVIDED IN WRITING WITHIN 30 DAYS OF
RECEIPT OF THIS NOTICE. TO DO SO, CONTACT YOUR LOCAL ON
SEMICONDUCTOR SALES OFFICE.

GPCN FORMAT: CUSTOMER



PRODUCT/PROCESS CHANGE NOTIFICATION

ISSUE DATE: 13-Oct-1999

NOTIFICATION #:10049

EFFECTIVE DATE: 20-Jan-2000

ISSUING DIVISION:PHX-PPD

DESCRIPTION AND PURPOSE

As part of the cost containment Programs for ON Semiconductor, SCG Seremban has qualified and will be converting the CASE-77 package to a plateless leadframe process. Devices built with the plateless leadframe have completed all internal Reliability qualification requirements per the AEC guidelines and is available upon request.

QUALIFICATION PLAN

Assembly Yield (Die Bond and Wire Bond), Wire Pull, Bond Shear Strength and electrical Data available upon request.

RELIABILITY DATA SUMMARY

Completed and passed the Reliability Test listed below:

- | | |
|----------------------|-----------------------------|
| 1- HTRB | 6- Solder Heat |
| 2- H3TRB | 7- Wire Pull Strength Test |
| 3- Autoclave | 8- Bond Shear Strength Test |
| 4- Temperature Cycle | 9- Die Shear Strength Test |
| 5- IOL | 10- HTSL |

ELECTRICAL CHARACTERISTIC SUMMARY

Data is available upon request.

CHANGED PART IDENTIFICATION

Customers may see plateless leadframe product starting with Date Code 950 or later.

FILE FORMAT: ASCII TEXT

FONT - Courier
SIZE - 12 Point
LINE - 70 characters/line
PAGE - 55 lines/page
PAGEBREAK CHARACTER - ^L (Control L)



AFFECTED DEVICE LIST (WITHOUT SPECIALS)

2N4918	,	2N4919	,	2N4920	,	2N4921
2N4922	,	2N4923	,	2N5190	,	2N5191
2N5192	,	2N5194	,	2N5195	,	2N5655
2N5657	,	2N6034	,	2N6035	,	2N6036
2N6038	,	2N6039	,	2N6070A	,	2N6071A
2N6071B	,	2N6071BT	,	2N6073A	,	2N6073B
2N6075	,	2N6075A	,	2N6075B	,	2N6240
BD135	,	BD136	,	BD137	,	BD138
BD139	,	BD139-010	,	BD140	,	BD159
BD179	,	BD180	,	BD234	,	BD237
BD238	,	BD435	,	BD435T	,	BD436
BD436T	,	BD437	,	BD437T	,	BD438
BD438T	,	BD439	,	BD440	,	BD441
BD442	,	BD675	,	BD675A	,	BD676
BD676A	,	BD677	,	BD677A	,	BD677T
BD678	,	BD678A	,	BD679	,	BD679A
BD680	,	BD680A	,	BD680T	,	BD681
BD682	,	BD682T	,	BD776	,	BD785
BD787	,	BD788	,	BD791	,	BD791T
BUH51	,	C106B	,	C106D	,	C106D1
C106M	,	C106M1	,	C106M1T	,	MCR106-006
MCR106-008	,	MCR506-002	,	MJE13003	,	MJE170
MJE171	,	MJE172	,	MJE180	,	MJE181
MJE182	,	MJE200	,	MJE210	,	MJE210T
MJE243	,	MJE253	,	MJE270	,	MJE271
MJE340	,	MJE3439	,	MJE344	,	MJE350
MJE371	,	MJE521	,	MJE700	,	MJE702
MJE703	,	MJE800	,	MJE802	,	MJE803
T2322B	,	TE02514LFVK	,	TPA0234		